



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	SOLVENT FREE PHOTORESIST STRIP AND RESIDUE REMOVAL PROCESSING FOR POST ETCHING OF LOW-K FILMS
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Application Number: 10/761122



Confirmation Number: 8790

First Named Applicant: HUONG NGUYEN

Attorney Docket Number: AMAT5735C1

Search string: (6214728 or 6130166 or 6124213 or 6074569
or 6062237 or 6046115 or 6043004 or 6037255
or 6030901 or 6024045 or 5811358 or 5681780
or 5660682 or 4357203 or 4028155).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
AD	1	6214728	2001-04-10	CHAN, ET AL.			
	2	6130166	2001-10-10	YEH			
	3	6124213	2000-09-26	USAMI, ET AL.			
	4	6074569	2000-06-13	KIZILOGLU, ET AL.			
	5	6062237	2000-05-16	BROWN, ET AL.			
	6	6046115	2000-04-04	MOLLOY, ET AL.			
	7	6043004	2000-03-28	KURIMOTO			
	8	6037255	2000-03-14	HUSSEIN, ET AL.			
	9	6030901	2000-02-29	HOPPER, ET AL.			
	10	6024045	2000-02-15	KIKUCHI, ET AL.			
	11	5811358	1998-09-22	TSENG, ET AL.			
	12	5681780	1997-10-28	MIHARA, ET AL.			
	13	5660682	1997-08-27	ZHAO, ET AL.			
	14	4357203	1982-11-02	ZELEZ			
AD	15	4028155	1977-06-07	JACOB			

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Comments